

ABSTRACT OF THE DISCLOSURE:

This invention relates to the production of transparent, shape-memorizing resin films by curing with radiation. The resin film composition comprising:

(a) an oligomer compound that has at least one acryloyl or methacryloyl group in the molecule and that has a glass transition temperature, Tg, of lower than 50°C after polymerization; and

(b) a low-molecular weight compound that has in its molecule one reactive double bond capable of polymerization with the oligomer compound (a) and that has a glass transition temperature, Tg, higher than 90°C after polymerization; or

(b') a mixture of two or more low-molecular weight compounds that have in their molecule one reactive double bond capable of copolymerization with the oligomer compound (a) and that have a glass transition temperature, Tg, higher than 90°C after polymerization.